# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**  
[List multiple models if applicable.]

HP 205 G2 AiO Business PC

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB, Memory, HDD PCA, ODD PCA, Adapter PCA</td>
<td>5</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries MB</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Adapter</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing radioactive substances

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>crisscross screw driver</td>
</tr>
<tr>
<td>Description #2</td>
<td>hexagon screw driver</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take off rear cover
2. Take off mother board cover
3. Remove all the cables from PCA
4. Take off MB
5. Remove memory from the PCA
6. Remove battery from the PCA
7. Take off speaker from the unit
8. Take off HDD from the unit
9. Take off system fan from the unit
10. Take off convertor board from the unit
11. Take off ODD from the unit
12. Take off button bracket
13. Take off camera from the unit
14. Take off main chassis
15. Take off panel from the unit
16. Open the power adapter by mechanical force.
17.
18.
19.
20.
21.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
<p>| | |</p>
<table>
<thead>
<tr>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>1. Take off rear cover</strong></td>
<td><strong>2. Take off mother board cover</strong></td>
</tr>
<tr>
<td>Rotate screw driver to release the screw and take off the rear cover.</td>
<td>Rotate screw driver to release screw and take off the mother board cover.</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#)
3. Remove all the cables from PCA.

4. Take off mother board

Rotate screw driver to release screw and take off mother board from the unit.
5. Remove memory from the PCA.
   Pull out memory by arrowhead.

6. Remove battery from the PCA.
7. Take off speaker from the unit.

Rotate screw driver to release the screw and take off speaker from the unit.

8. Take off HDD from the unit.

8.1: Rotate screw driver to release screw and remove HDD cage.

8.2: Pull out the HDD by
8.3: Take off HDD from HDD cage
9. Take off system fan from the unit.
   Rotate screw driver to release screw and remove system fan from the unit.

10. Take off convertor board from the unit.
    10.1. remove cable from convertor board
    10.2. rotate screw driver to release convertor board screw.
11. Take off ODD from the unit.
11.1: remove ODD bracket

11.2: pull out the ODD by arrowhead
12. Take off the button bracket.

13. Take off camera by arrowhead.

14. Take off main chassis from the unit.
14.1 Rotate screw driver to release the screw

14.2 Release 5 latches from main chassis by pulling the latches outwards.

14.3 pull out the main chassis by arrowhead.
15. Take off the panel from the unit.

16. Open the power adapter by mechanical force. Remove PCA and Capacitor >25mm in size.